#### Supplier Name: Contact Info: Form/Declaration Type: Created on:

# Texas Instruments Inc. (DUNS# 00-732-1904) ti.com/support Distribute - RoHS and IEC 62474 DB

05/09/2022

# Details for "TLC3702QDRQ1" **Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TLC3702QDRQ1	NIPDAU	Level-1-260C-UNLIM	TI AGUASCALIENTES	D   8	4.9x3.9x1.75	107.6

### \*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

### **Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

## **Component Information**

				Homogeneous Material Level		Component Level			
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm		
Bond Wire									
Precious Metals	Gold	7440-57-5	0.104499	100	1000000	0.09709	971		
Sub-Total			0.104499	100	1000000	0.09709	971		
Die Attach Adhesive									
Precious Metals	Silver	7440-22-4	0.213616	79	790000	0.19847	1985		
Thermoplastics	Epoxy	85954-11-6	0.056784	21	210000	0.052758	528		
Sub-Total			0.2704	100	1000000	0.251228	2512		
Lead Frame									
Copper and Its Alloys	Copper	7440-50-8	40.49388	96.414	964140	37.622796	376228		
Copper and Its Alloys	Iron	7439-89-6	1.092	2.6	26000	1.014575	10146		
Copper and Its Alloys	Phosphorus	7723-14-0	0.063	0.15	1500	0.058533	585		
Nickel and Its Alloys	Nickel	7440-02-0	0.336	0.8	8000	0.312177	3122		
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.0042	0.01	100	0.003902	39		
Precious Metals	Gold	7440-57-5	0.0042	0.01	100	0.003902	39		
Precious Metals	Palladium	7440-05-3	0.00672	0.016	160	0.006244	62		
Sub-Total			42	100	1000000	39.02213	390221		
Lead Frame Plating									
Nickel and Its Alloys	Nickel	7440-02-0	3.99504	95.12	951200	3.711785	37118		
Precious Metals	Gold	7440-57-5	0.03276	0.78	7800	0.030437	304		
Precious Metals	Palladium	7440-05-3	0.1722	4.1	41000	0.159991	1600		
Sub-Total			4.2	100	1000000	3.902213	39022		
Mold Compound									
Other Inorganic Materials	Fused Silica	60676-86-0	52.864261	88	880000	49.116096	491161		
Other Plastics and Rubber	Carbon Black	1333-86-4	0.180219	0.3	3000	0.167441	1674		
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.330402	0.550001	5500	0.306976	3070		
Thermoplastics	Ероху	85954-11-6	6.698142	11.15	111500	6.223233	62232		
Sub-Total			60.073024	100	1000000	55.813746	558137		
Semiconductor Device									
Ceramics / Glass	Doped Silicon	7440-21-3	0.983312	100	1000000	0.913594	9136		
Sub-Total			0.983312	100	1000000	0.913594	9136		
Total			107.631235			100	1000000		

### Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

# See Glossary of Terms for more details.

## Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

## Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

### Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU ROHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

#### Important Information/Disclaime

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is." For additional information, please contact TI customer support.

#### Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/09/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

ROHS Exempt: Means TI semiconductor products that contain lead (Pb) above the ROHS Annex II threshold, but that fall within one of the specific ROHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <= 1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <= 1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.